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RESPONSE UNDER 37 C.F.R. § 1.116  
EXPEDITED PROCEDURE  
EXAMINING GROUP 1765

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

<b>Applicants:</b>	Diane C. Boyd et al.	<b>Docket:</b>	YOR920030335US1 (16900)
<b>Serial No.:</b>	10/725,848	<b>Examiner:</b>	Patricia Ann George
<b>Filed:</b>	December 2, 2003	<b>Art Unit:</b>	1765
<b>For:</b>	ULTRA-THIN Si MOSFET DEVICE STRUCTURE AND METHOD OF MANUFACTURE	<b>Dated:</b>	May 19, 2006
		<b>Confirmation No:</b>	3237

Mail Stop AF  
Commissioner for Patents  
United States Patent Office  
Alexandria, VA 22313-1450

**RESPONSE UNDER 37 C.F.R. §1.116**

*entered per REC  
filed 7/21/06  
la*

Sir:


In response to the Office Action dated March 22, 2006, applicants submit the following amendments and remarks for entry of record in the above-identified patent application..

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**CERTIFICATE OF MAILING UNDER 37 C.F.R. §1.8(a)**

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner For Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on May 19, 2006.

Dated: May 19, 2006

  
Leslie S. Szivos, Ph.D.